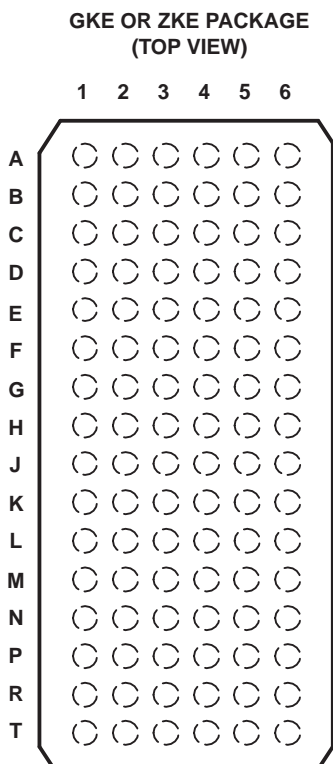


FEATURES

- Member of Texas Instruments Widebus+™ Family
- State-of-the-Art Advanced BiCMOS Technology (ABT) Design for 3.3-V Operation and Low Static-Power Dissipation
- Typical V_{OLP} (Output Ground Bounce) <0.8 V at $V_{CC} = 3.3$ V, $T_A = 25^\circ\text{C}$
- I_{off} and Power-Up 3-State Support Hot Insertion
- Supports Mixed-Mode Signal Operation (5-V Input and Output Voltages With 3.3-V V_{CC})
- Supports Unregulated Battery Operation Down to 2.7 V
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)



TERMINAL ASSIGNMENTS

	1	2	3	4	5	6
A	1Y2	1Y1	1 \overline{OE}	2 \overline{OE}	1A1	1A2
B	1Y4	1Y3	GND	GND	1A3	1A4
C	2Y2	2Y1	1 V_{CC}	1 V_{CC}	2A1	2A2
D	2Y4	2Y3	GND	GND	2A3	2A4
E	3Y2	3Y1	GND	GND	3A1	3A2
F	3Y4	3Y3	1 V_{CC}	1 V_{CC}	3A3	3A4
G	4Y2	4Y1	GND	GND	4A1	4A2
H	4Y3	4Y4	4 \overline{OE}	3 \overline{OE}	4A4	4A3
J	5Y2	5Y1	5 \overline{OE}	6 \overline{OE}	5A1	5A2
K	5Y4	5Y3	GND	GND	5A3	5A4
L	6Y2	6Y1	2 V_{CC}	2 V_{CC}	6A1	6A2
M	6Y4	6Y3	GND	GND	6A3	6A4
N	7Y2	7Y1	GND	GND	7A1	7A2
P	7Y4	7Y3	2 V_{CC}	2 V_{CC}	7A3	7A4
R	8Y2	8Y1	GND	GND	8A1	8A2
T	8Y3	8Y4	8 \overline{OE}	7 \overline{OE}	8A4	8A3

DESCRIPTION/ORDERING INFORMATION

The SN74LVT32244 is a 32-bit buffer and line driver designed for low-voltage (3.3-V) V_{CC} operation, but with the capability to provide a TTL interface to a 5-V system environment.

ORDERING INFORMATION

T_A	PACKAGE ⁽¹⁾		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	BGA – GKE	Reel of 1000	SN74LVT32244GKER	VJ244
	BGA – ZKE (Pb-free)		SN74LVT32244ZKER	

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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SN74LVT32244
3.3-V ABT 32-BIT BUFFER/DRIVER
WITH 3-STATE OUTPUTS

SCBS748C—OCTOBER 2000—REVISED NOVEMBER 2006

DESCRIPTION/ORDERING INFORMATION (CONTINUED)

This device can be used as eight 4-bit buffers, four 8-bit buffers, two 16-bit buffers, or one 32-bit buffer. The device provides true outputs and has symmetrical active-output-enable (\overline{OE}) inputs. It is designed specifically to improve both the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters.

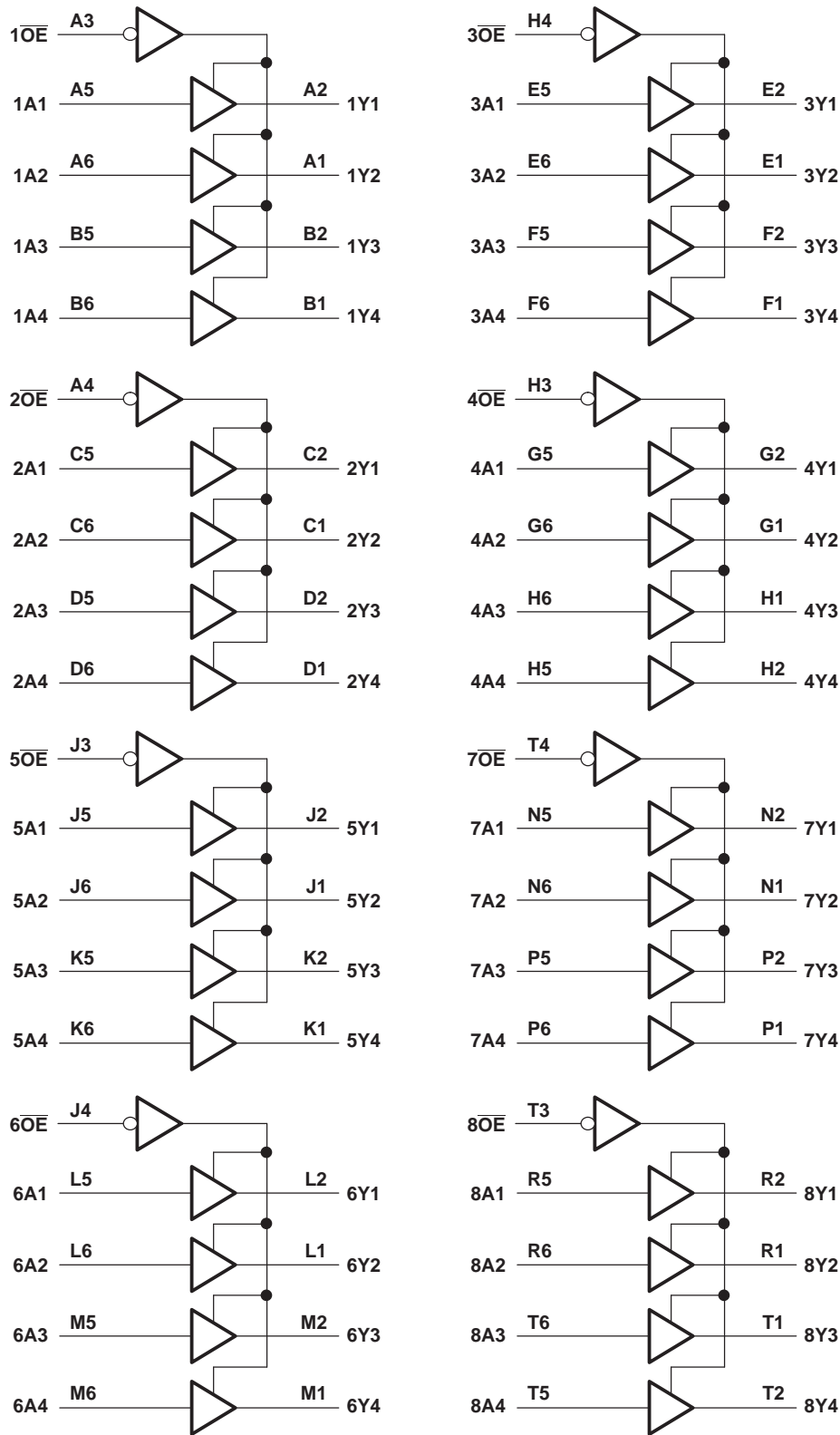
To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

This device is fully specified for hot-insertion applications using I_{off} and power-up 3-state. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down. The power-up 3-state circuitry places the outputs in the high-impedance state during power up and power down, which prevents driver conflict.

FUNCTION TABLE
(each 4-bit buffer/driver)

INPUTS		OUTPUT Y
\overline{OE}	A	
L	H	H
L	L	L
H	X	Z

LOGIC DIAGRAM (POSITIVE LOGIC)



SN74LVT32244

3.3-V ABT 32-BIT BUFFER/DRIVER WITH 3-STATE OUTPUTS

SCBS748C—OCTOBER 2000—REVISED NOVEMBER 2006

Absolute Maximum Ratings⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
V_{CC}	Supply voltage range	-0.5	4.6	V
V_I	Input voltage range ⁽²⁾	-0.5	7	V
V_O	Voltage range applied to any output in the high-impedance or power-off state ⁽²⁾	-0.5	7	V
V_O	Voltage range applied to any output in the high state ⁽²⁾	-0.5	$V_{CC} + 0.5$	V
I_O	Current into any output in the low state		128	mA
I_O	Current into any output in the high state ⁽³⁾		64	mA
I_{IK}	Input clamp current	$V_I < 0$	-50	mA
I_{OK}	Output clamp current	$V_O < 0$	-50	mA
θ_{JA}	Package thermal impedance ⁽⁴⁾	GKE/ZKE package		40 °C/W
T_{stg}	Storage temperature range	-65	150	°C

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

(3) This current flows only when the output is in the high state and $V_O > V_{CC}$.

(4) The package thermal impedance is calculated in accordance with JESD 51-7.

Recommended Operating Conditions⁽¹⁾

		MIN	MAX	UNIT
V_{CC}	Supply voltage	2.7	3.6	V
V_{IH}	High-level input voltage	2		V
V_{IL}	Low-level input voltage		0.8	V
V_I	Input voltage		5.5	V
I_{OH}	High-level output current		-32	mA
I_{OL}	Low-level output current		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		10 ns/V
$\Delta t/\Delta V_{CC}$	Power-up ramp rate	200		μs/V
T_A	Operating free-air temperature	-40	85	°C

(1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP ⁽¹⁾	MAX	UNIT
V_{IK}		$V_{CC} = 2.7\text{ V}$,	$I_I = -18\text{ mA}$			-1.2	V
V_{OH}		$V_{CC} = 2.7\text{ V to }3.6\text{ V}$,	$I_{OH} = -100\text{ }\mu\text{A}$	$V_{CC} - 0.2$			V
		$V_{CC} = 2.7\text{ V}$,	$I_{OH} = -8\text{ mA}$	2.4			
		$V_{CC} = 3\text{ V}$,	$I_{OH} = -32\text{ mA}$	2			
V_{OL}	$V_{CC} = 2.7\text{ V}$		$I_{OL} = 100\text{ }\mu\text{A}$			0.2	V
			$I_{OL} = 24\text{ mA}$			0.5	
	$V_{CC} = 3\text{ V}$		$I_{OL} = 16\text{ mA}$			0.4	
			$I_{OL} = 32\text{ mA}$			0.5	
			$I_{OL} = 64\text{ mA}$			0.55	
I_I		$V_{CC} = 0\text{ or }3.6\text{ V}$,	$V_I = 5.5\text{ V}$			10	μA
	Control inputs	$V_{CC} = 3.6\text{ V}$,	$V_I = V_{CC}\text{ or GND}$			± 1	
	Data inputs	$V_{CC} = 3.6\text{ V}$	$V_I = V_{CC}$			1	
$V_I = 0$					-5		
I_{off}		$V_{CC} = 0$,	$V_I\text{ or }V_O = 0\text{ to }4.5\text{ V}$			± 100	μA
I_{OZH}		$V_{CC} = 3.6\text{ V}$,	$V_O = 3\text{ V}$			5	μA
I_{OZL}		$V_{CC} = 3.6\text{ V}$,	$V_O = 0.5\text{ V}$			-5	μA
I_{OZPU}		$V_{CC} = 0\text{ to }1.5\text{ V}$, $V_O = 0.5\text{ V to }3\text{ V}$, $\overline{OE} = \text{don't care}$				± 100	μA
I_{OZPD}		$V_{CC} = 1.5\text{ V to }0$, $V_O = 0.5\text{ V to }3\text{ V}$, $\overline{OE} = \text{don't care}$				± 100	μA
I_{CC}		$V_{CC} = 3.6\text{ V}$, $I_O = 0$, $V_I = V_{CC}\text{ or GND}$	Outputs high			0.38	mA
			Outputs low			10	
			Outputs disabled			0.38	
$\Delta I_{CC}^{(2)}$		$V_{CC} = 3\text{ V to }3.6\text{ V}$, One input at $V_{CC} - 0.6\text{ V}$, Other inputs at $V_{CC}\text{ or GND}$				0.2	mA
C_i		$V_I = 3\text{ V or }0$			4		pF
C_o		$V_O = 3\text{ V or }0$			9		pF

 (1) All typical values are at $V_{CC} = 3.3\text{ V}$, $T_A = 25^\circ\text{C}$.

 (2) This is the increase in supply current for each input that is at the specified TTL voltage level, rather than V_{CC} or GND.

SN74LVT32244
3.3-V ABT 32-BIT BUFFER/DRIVER
WITH 3-STATE OUTPUTS

SCBS748C–OCTOBER 2000–REVISED NOVEMBER 2006

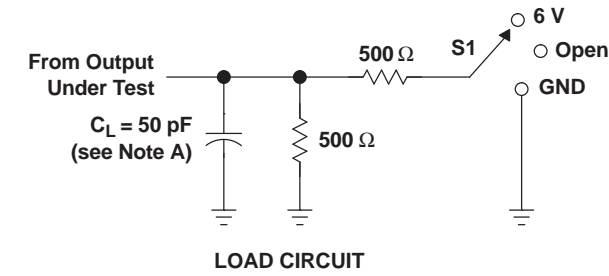
Switching Characteristics

over recommended operating free-air temperature range (unless otherwise noted) (see [Figure 1](#))

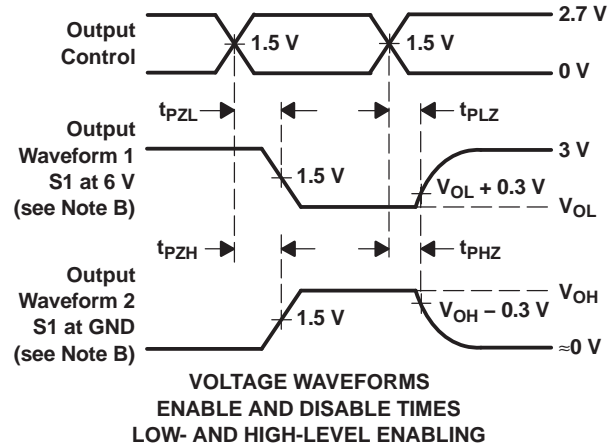
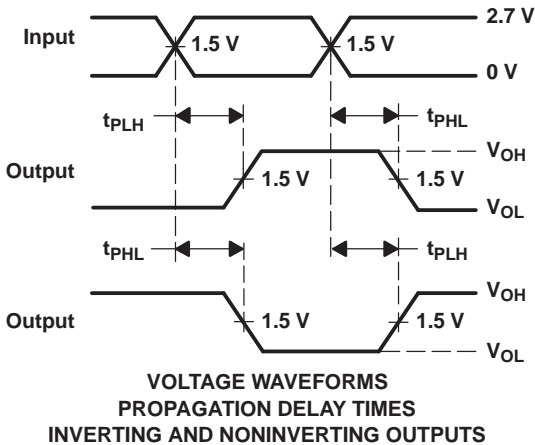
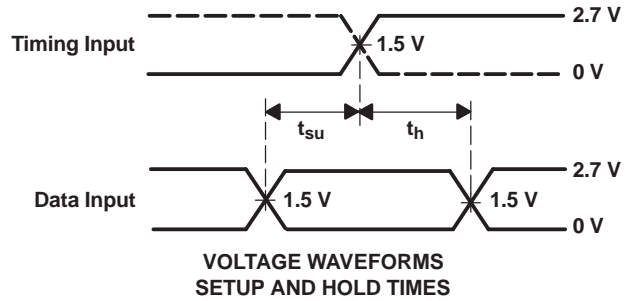
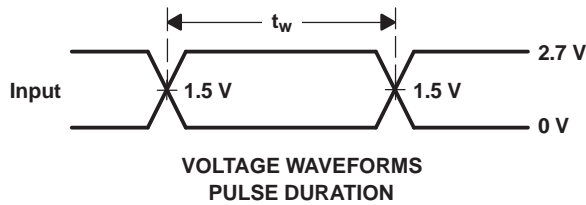
PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 3.3\text{ V}$ $\pm 0.3\text{ V}$			$V_{CC} = 2.7\text{ V}$		UNIT
			MIN	TYP ⁽¹⁾	MAX	MIN	MAX	
t_{PLH}	A	Y	1.2	2.3	3.2	3.7		ns
t_{PHL}			1.2	2	3.2	3.7		
t_{PZH}	\overline{OE}	Y	1.2	2.6	4	5		ns
t_{PZL}			1.2	2.7	4	5		
t_{PHZ}	\overline{OE}	Y	2.2	3.3	4.5	5		ns
t_{PLZ}			2	3.1	4.2	4.4		
$t_{sk(LH)}$					0.5			ns
$t_{sk(HL)}$					0.5			

(1) All typical values are at $V_{CC} = 3.3\text{ V}$, $T_A = 25^\circ\text{C}$.

PARAMETER MEASUREMENT INFORMATION



TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	6 V
t_{PHZ}/t_{PZH}	GND



- NOTES: A. C_L includes probe and jig capacitance.
 B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
 D. The outputs are measured one at a time, with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74LVT32244GKER	OBSOLETE	LFBGA	GKE	96		TBD	Call TI	Call TI	-40 to 85	VJ244	
SN74LVT32244ZKER	OBSOLETE	LFBGA	ZKE	96		TBD	Call TI	Call TI	-40 to 85	VJ244	

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

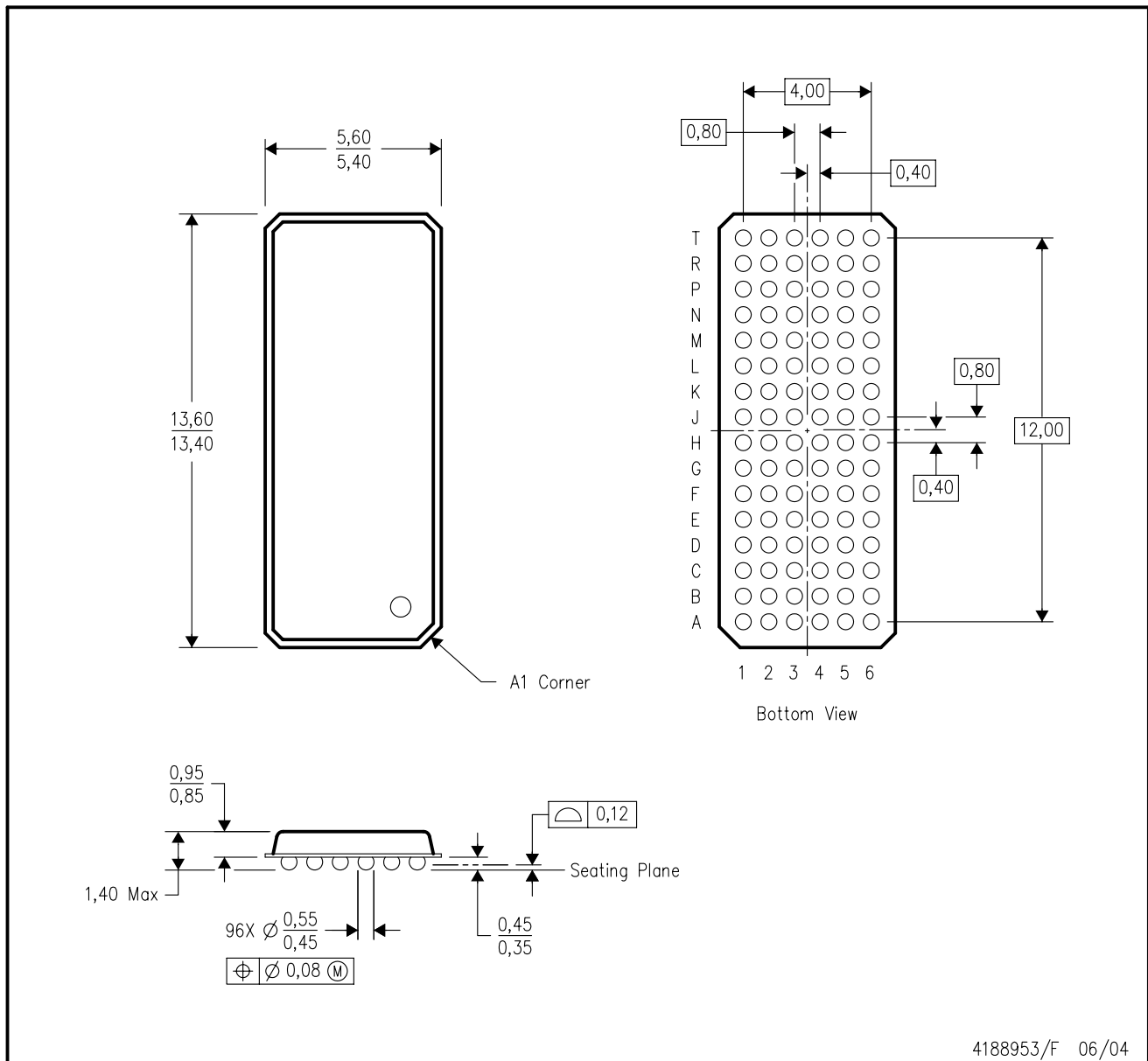
(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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GKE (R-PBGA-N96)

PLASTIC BALL GRID ARRAY



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Falls within JEDEC MO-205 variation CC.
 - D. This package is tin-lead (SnPb). Refer to the 96 ZKE package (drawing 4204493) for lead-free.

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